

672-Pin Thermally Enhanced FineLine Ball-Grid Array (FBGA)

- All dimensions and tolerances conform to ANSI Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Orientation of the package is shown by a chamfer and/or a pin 1 mark.

Package Information	
Description	Specification
Ordering Code Reference	F
Package Acronym	FBGA
Lead Material	Tin-lead alloy (63/37)
Lead Finish	N/A
JEDEC Outline	MS-034
JEDEC Option	AAL-1
Maximum Lead Coplanarity	0.008 inches (0.20 mm)
Weight	4.9 g
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Figure Reference			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	–	–	3.50
A1	0.30	–	–
A2	0.25	–	3.00
A3	–	–	2.50
b	0.50	0.60	0.70
e	1.00 BSC		
D/E	27.00 BSC		
M	26		

Package Outline

